

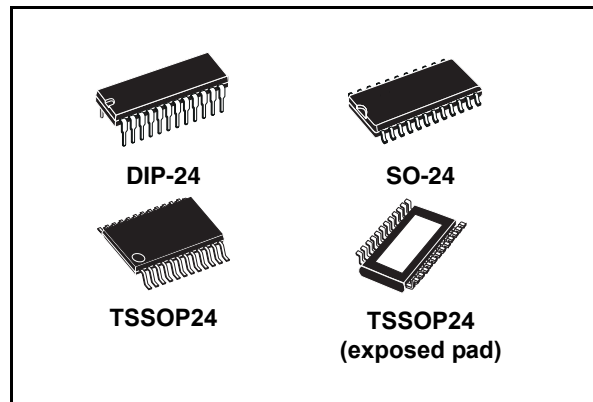


STP16CPS05

Low voltage 16-Bit constant current LED sink driver
with auto power saving

Features

- Low voltage power supply down to 3V
- 16 constant current output channels
- Adjustable output current through external resistor
- Serial Data IN/Parallel Data OUT
- Auto power-saving feature minimizes the quiescent current if no active data is detected on the latches
- Can be driven by a 3.3V microcontroller
- Output current: 5-80mA
- Max clock frequency 30MHz
- ESD protection 2.5kV HBM, 200V MM



Description

The STP16CPS05 is a monolithic, low voltage, low current power 16-bit shift register designed for LED panel displays. The STP16CPS05 contains a 16-bit serial-in, parallel-out shift register that feeds a 16-bit, D-type storage register. In the output stage, sixteen regulated current sources provide from 5mA to 80mA constant current to drive the LEDs.

The Auto Power Shut-Down and Auto Power-ON feature allows the device to save power without any external intervention.

The output current setup time is 40ns (typ), thus improving the system performance.

The LEDs' brightness can be controlled by using an external resistor to adjust the STP16CPS05 output current.

The STP16CPS05 guarantees a 20V output driving capability, allowing users to connect more LEDs in series. The high clock frequency, 30MHz, makes the device suitable for high data rate transmission. The 3.3V voltage supply is useful in applications that interface with a 3.3V microcontroller.

Order codes

Part number	Package	Packaging
STP16CPS05B1R	DIP-24	15 parts per tube
STP16CPS05MTR	SO-24	1000 parts per reel
STP16CPS05TTR	TSSOP24	2500 parts per reel
STP16CPS05XTR	TSSOP24 Exposed Pad	2500 parts per reel

Contents

1	Summary description	3
1.1	Pin connection and description	3
2	Electrical ratings	4
2.1	Absolute maximum ratings	4
2.2	Thermal data	4
2.3	Recommended operating conditions	5
3	Electrical characteristics	6
4	Equivalent circuit and outputs	8
5	Timing diagrams	10
6	Typical characteristics	13
7	Test circuit	16
8	Package mechanical data	18
9	Revision history	25

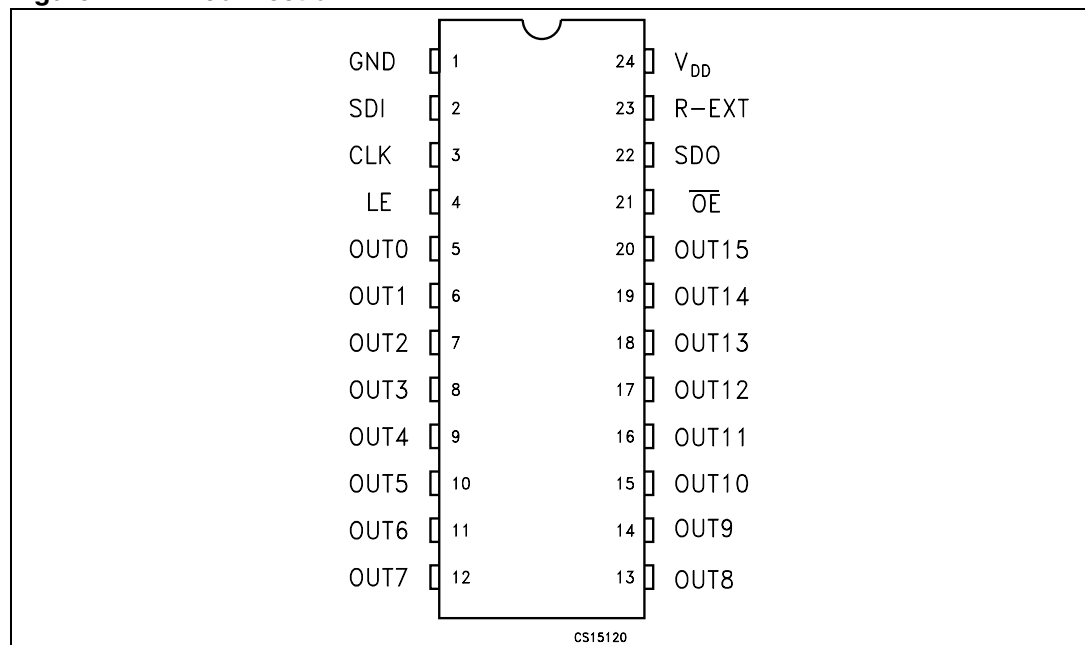
1 Summary description

Table 1. Current accuracy

Output voltage	Current accuracy		Output current	V _{DD}	temp.
	Between bits	Between ICs			
≥ 1.0V	± 3%	± 8%	≥15 to 80 mA	3.3V to 5V	25°C
≥ 0.2V	± 6%	± 8%	5 to 15 mA		

1.1 Pin connection and description

Figure 1. Pin connection



Note: The exposed pad is electrically not connected

Table 2. Pin description

PIN N°	Symbol	Name and function
1	GND	Ground Terminal
2	SDI	Serial data input terminal
3	CLK	Clock input terminal
4	LE	Latch input terminal
5-20	OUT 0-15	Output terminal
21	$\overline{OE}$	Input terminal of output enable (active low)
22	SDO	Serial data out terminal
23	R-EXT	Input terminal of an external resistor for constant current programming
24	V _{DD}	Supply voltage terminal

2 Electrical ratings

2.1 Absolute maximum ratings

Stressing the device above the rating listed in the “Absolute Maximum Ratings” table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

Table 3. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DD}	Supply voltage	0 to 7	V
V_O	Output voltage	-0.5 to 20	V
I_O	Output current	80	mA
V_I	Input voltage	-0.4 to $V_{DD}+0.4$	V
I_{GND}	GND terminal current	1300	mA
f_{CLK}	Clock frequency	50	MHz

2.2 Thermal data

Table 4. Thermal data

Symbol	Parameter		Value	Unit
T_{OPR}	Operating temperature range		-40 to +125	°C
T_{STG}	Storage temperature range		-55 to +150	°C
R_{thJC}	Thermal resistance junction-case	DIP-24	60	°C/W
		TSSOP24	85	°C/W
		TSSOP24 ⁽¹⁾ Exposed Pad	37.5	°C/W
		SO-24	75	°C/W

1. The exposed pad should be soldered directly to the PCB to realize the thermal benefits.

2.3 Recommended operating conditions

Table 5. Recommended operating conditions at 25°C

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{DD}	Supply voltage		3.0		5.5	V
V_O	Output voltage				20	V
I_O	Output current	OUTn	3		80	mA
I_{OH}	Output current	SERIAL-OUT			+1	mA
I_{OL}	Output current	SERIAL-OUT			-1	mA
V_{IH}	Input voltage		$0.7V_{DD}$		$V_{DD}+0.3$	V
V_{IL}	Input voltage		-0.3		$0.3V_{DD}$	V
t_{wLAT}	LE pulse width	$V_{DD} = 3.3V \text{ to } 5.0V$	20			ns
t_{wCLK}	CLK pulse width		16			ns
t_{wEN}	/OE pulse width		200			ns
$t_{SETUP(D)}$	Setup time for DATA		20			ns
$t_{HOLD(D)}$	Hold time for DATA		15			ns
$t_{SETUP(L)}$	Setup time for LATCH		15			ns
f_{CLK}	Clock frequency	Cascade operation ⁽¹⁾			30	MHz

1. If the device is connected in cascade, it may not be possible achieve the maximum data transfer. Please considered the timings carefully.

3 Electrical characteristics

Table 6. Electrical characteristics
($V_{DD}=3.3V$ to $5V$, $T = 25^{\circ}C$, unless otherwise specified.)

Symbol	Parameter	Test conditions	Min	Typ	Max	Unit
V_{IH}	Input voltage high level		$0.7V_{DD}$		V_{DD}	V
V_{IL}	Input voltage low level		GND		$0.3V_{DD}$	V
I_{OH}	Output leakage current	$V_{OH} = 20V$			10	μA
V_{OL}	Output voltage (Serial-OUT)	$I_{OL} = 1mA$			0.4	V
V_{OH}	Output voltage (Serial-OUT)	$I_{OH} = -1mA$	$V_{DD}-0.4V$			V
I_{OL1}	Output current	$V_O = 0.3VR_{EXT} = 976\Omega$		20		mA
I_{OL2}		$V_O = 1.2VR_{EXT} = 241\Omega$		80		mA
ΔI_{OL1}	Output current error between bit (All Output ON)	$V_O = 0.3VR_{EXT} = 976\Omega$		± 2	± 3	%
ΔI_{OL2}		$V_O = 1.2VR_{EXT} = 241\Omega$		± 2	± 3	%
$R_{SIN(up)}$	Pull-up resistor		150	300	600	$K\Omega$
$R_{SIN(down)}$	Pull-down resistor		100	200	400	$K\Omega$
$I_{DD(SH)}$	Shut-down current All Latched Data = L	$V_{DD} = 3.3V$		70	120	μA
		$V_{DD} = 5V$		100	150	μA
$I_{DD(OFF1)}$	Supply current (OFF)	$R_{EXT} = 970$ OUT 0 to 15 = OFF		4		mA
$I_{DD(OFF2)}$		$R_{EXT} = 240$ OUT 0 to 15 = OFF		11.2		
$I_{DD(ON1)}$	Supply current (ON)	$R_{EXT} = 970$ OUT 0 to 15 = ON		4.5		
$I_{DD(ON2)}$		$R_{EXT} = 240$ OUT 0 to 15 = ON		11.7		
Thermal	Thermal protection			170		$^{\circ}C$

Table 7. Switching characteristics ($V_{DD} = 5V$, $T = 25^{\circ}C$, unless otherwise specified.)

Symbol	Parameter	Test conditions		Min	Typ	Max	Unit		
t _{PLH1}	Propagation Delay Time, CLK- $\overline{OUTn}$, LE = H, $\overline{OE}$ = L	V _{DD} = 3.3 V V _{IL} = GND I _O = 20mA R _{EXT} = 1K Ω	V _{IH} = V _{DD} C _L = 10pF V _L = 3.0 V R _L = 60 Ω	V _{DD} = 3.3V		50	70	ns	
				V _{DD} = 5V		28	40		
t _{PLH2}	Propagation Delay Time, LE- $\overline{OUTn}$, $\overline{OE}$ = L			V _{DD} = 3.3V		48	70	ns	
				V _{DD} = 5V		25	40		
t _{PLH3}	Propagation Delay Time, $\overline{OE}$ - $\overline{OUTn}$, LE = H			V _{DD} = 3.3V		55	75	ns	
				V _{DD} = 5V		35	45		
t _{PLH}	Propagation Delay Time, CLK-SDO			V _{DD} = 3.3V		11	16	ns	
				V _{DD} = 5V		8	12		
t _{PHL1}	Propagation Delay Time, CLK- $\overline{OUTn}$, LE = H, $\overline{OE}$ = L			V _{DD} = 3.3V		22	30	ns	
				V _{DD} = 5V		17	25		
t _{PHL2}	Propagation Delay Time, $\overline{LE}$ - $\overline{OUTn}$, $\overline{OE}$ = L			V _{DD} = 3.3V		7	10	ns	
				V _{DD} = 5V		4	6		
t _{PHL3}	Propagation Delay Time, $\overline{OE}$ - $\overline{OUTn}$, LE = H			V _{DD} = 3.3V		18	30	ns	
				V _{DD} = 5V		15	25		
t _{PHL}	Propagation Delay Time, CLK-SDO			V _{DD} = 3.3V		12	18	ns	
				V _{DD} = 5V		8	12		
t _{ON}	Output Rise Time 10~90% of voltage waveform			V _{DD} = 3.3V		40	80	ns	
				V _{DD} = 5V		22	35		
t _{OFF}	Output Fall Time 90~10% of voltage waveform			V _{DD} = 3.3V		11	15	ns	
				V _{DD} = 5V		18	25		
t _r	CLK Rise Time ⁽¹⁾							5000	ns
t _f	CLK Fall Time ⁽¹⁾							5000	ns

1. In order to achieve high cascade data transfer, please consider t_r/t_f timings carefully.

4 Equivalent circuit and outputs

Figure 2. $\overline{\text{OE}}$ Terminal

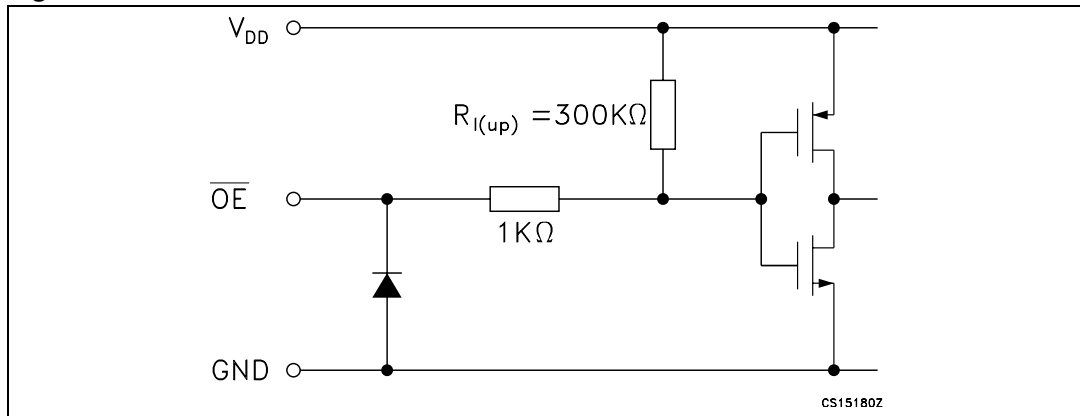


Figure 3. LE Terminal

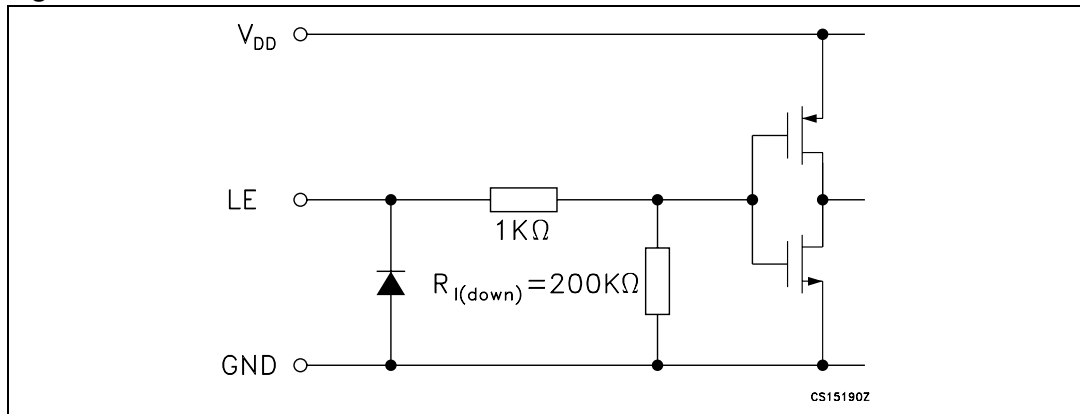


Figure 4. CLK, SDI Terminal

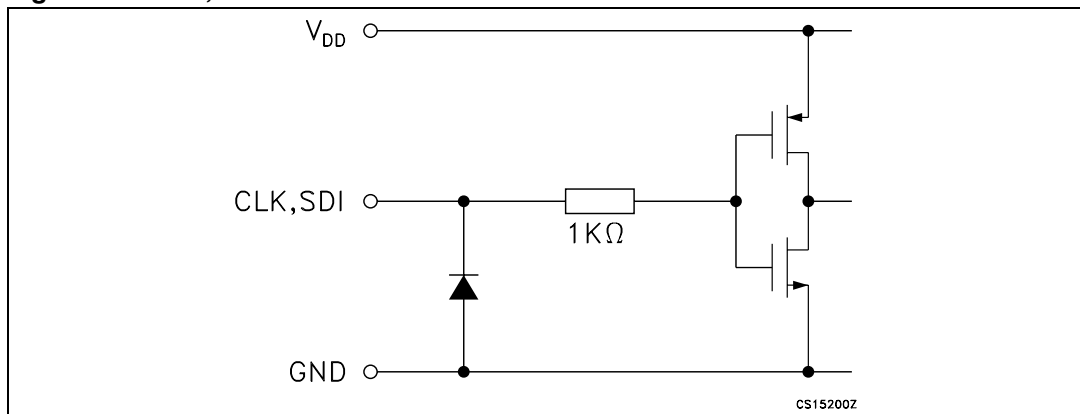


Figure 5. SDO Terminal

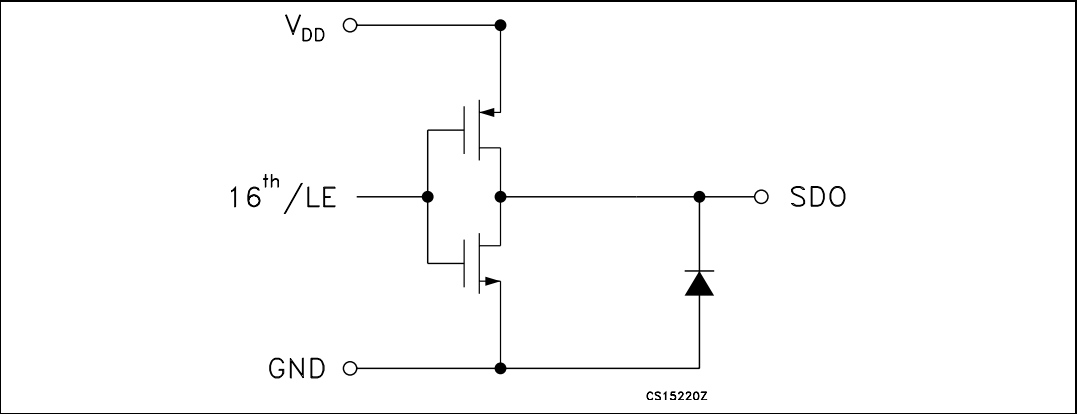
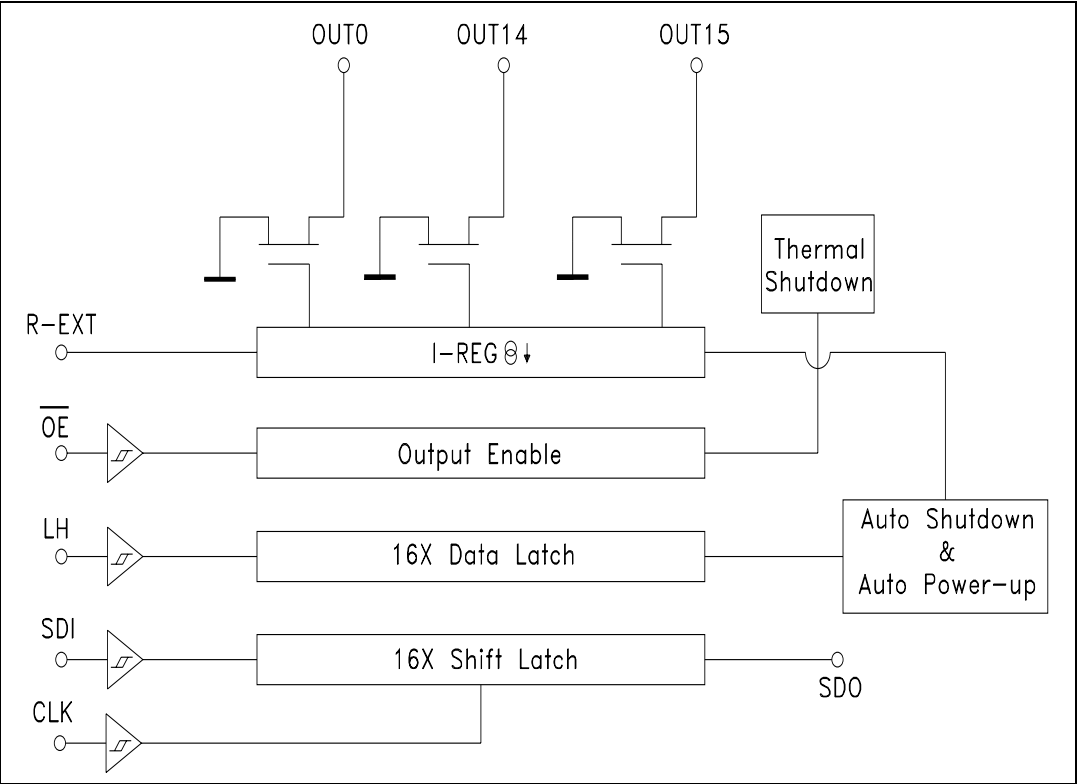


Figure 6. Block diagram



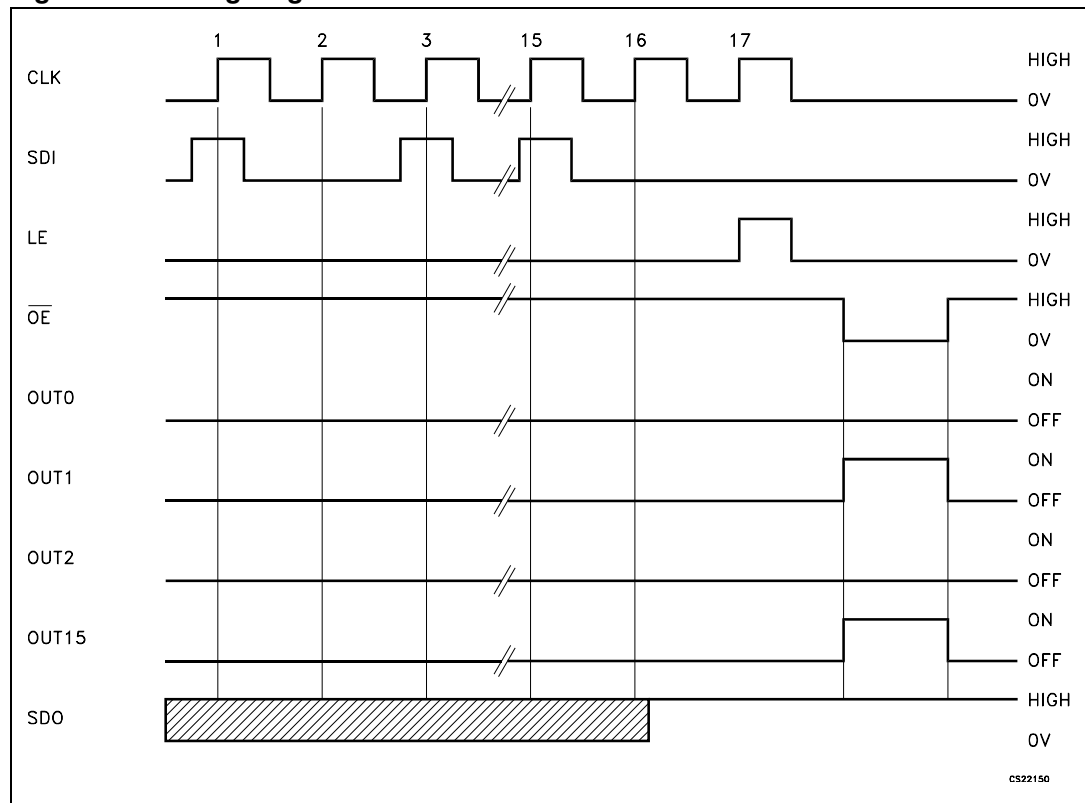
5 Timing diagrams

Table 8. Truth Table

CLOCK	LE	/OE	SERIAL-IN	OUT0 OUT7 OUT15	SDO
	H	L	Dn	Dn Dn - 7 Dn -15	Dn - 15
	L	L	Dn + 1	No Change	Dn - 14
	H	L	Dn + 2	Dn - 2 Dn - 5 Dn -13	Dn - 13
	X	L	Dn + 3	Dn - 2 Dn - 5 Dn -13	Dn - 13
	X	L	Dn + 3	ON	Dn - 13

Note: $OUT0$ to $OUT15$ = ON when $Dn = H$; $OUT0$ to $OUT15$ = OFF when $Dn = L$.

Figure 7. Timing diagram



Note: The latches circuit holds data when the LE terminal is Low.

- 1 When LE terminal is at High level, latch circuit hold the data it passes from the input to the output.
- 2 When OE terminal is at Low level, output terminals $OUT0$ to $OUT15$ respond to the data, either ON or OFF.
- 3 When OE terminal is at High level, it switches off all the data on the output terminal.

Table 9. Enable IO: shut-down truth table

CLOCK	LE	SDI ₀ SDI ₇ SDI ₁₅	SH	Auto Power-up	OUTn
	H	All = L	Active	Not Active	OFF
	L	No Change	No Change	No Change	No Change
	H	One or more = H	Not Active	Active	X

Note: At the Power-up the device starts in Shut-Down mode.

Figure 8. Clock, serial-in, serial-out

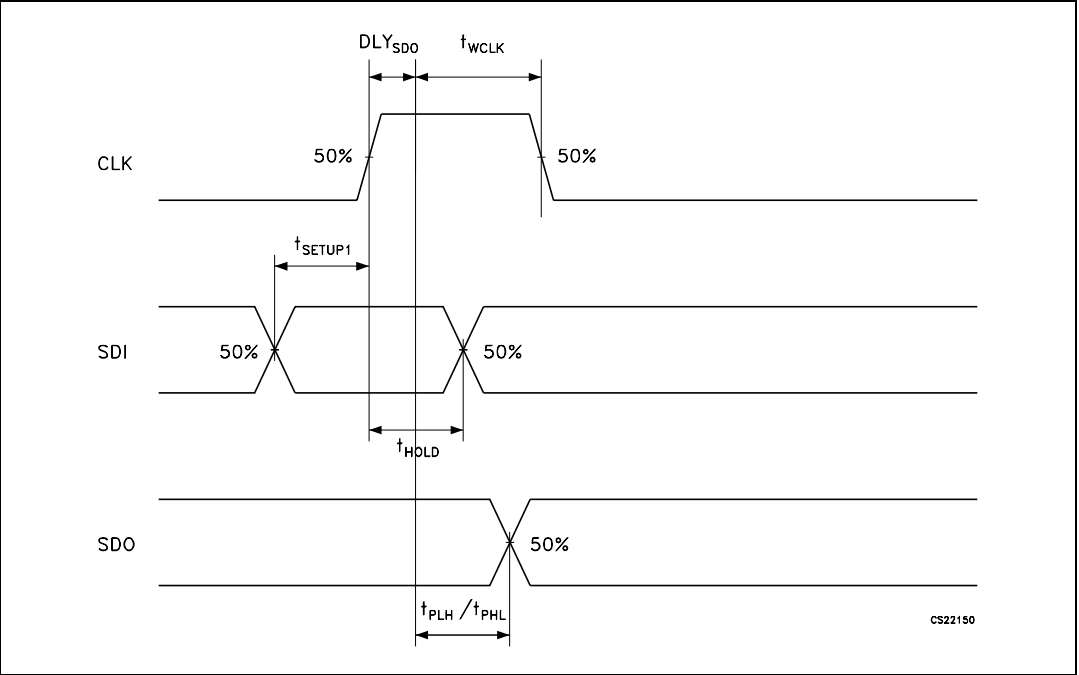


Figure 9. Clock, serial-in, latch, enable, outputs

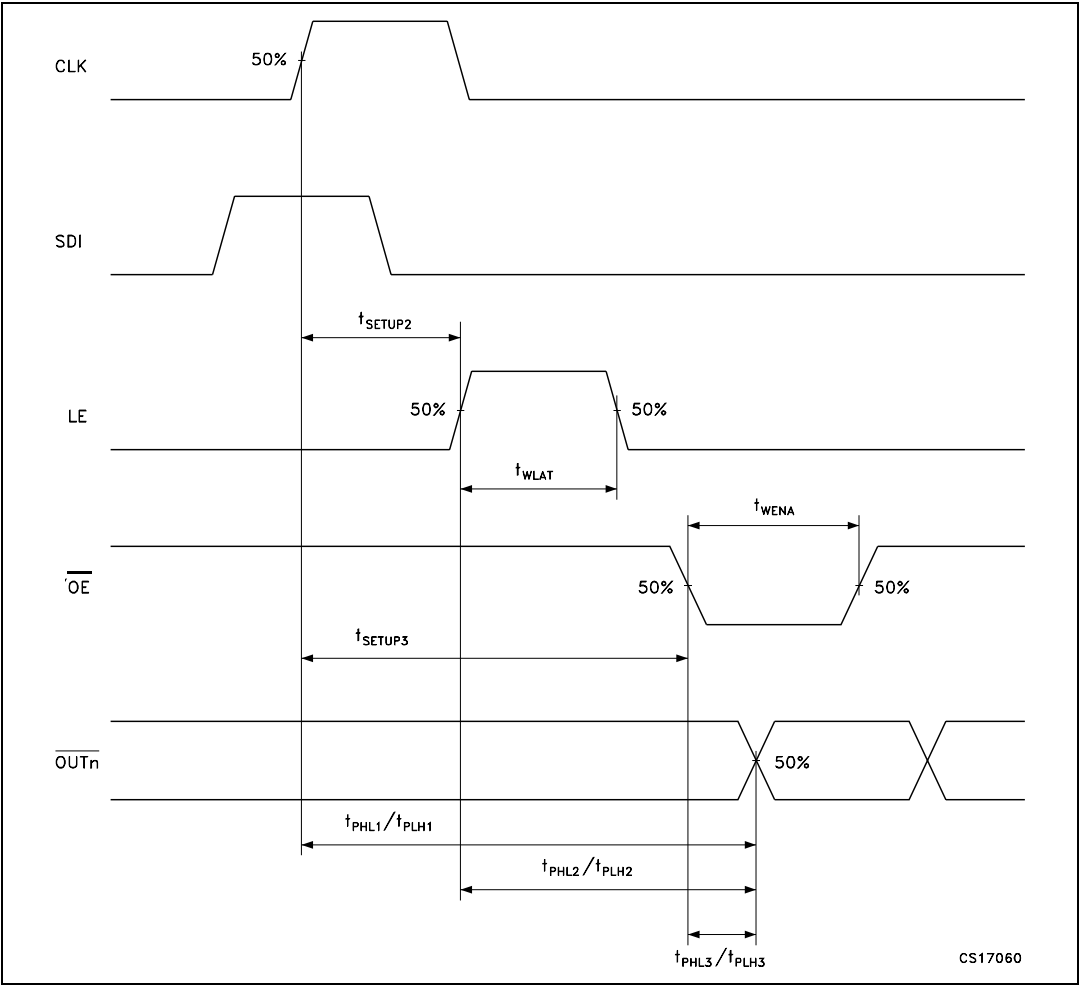
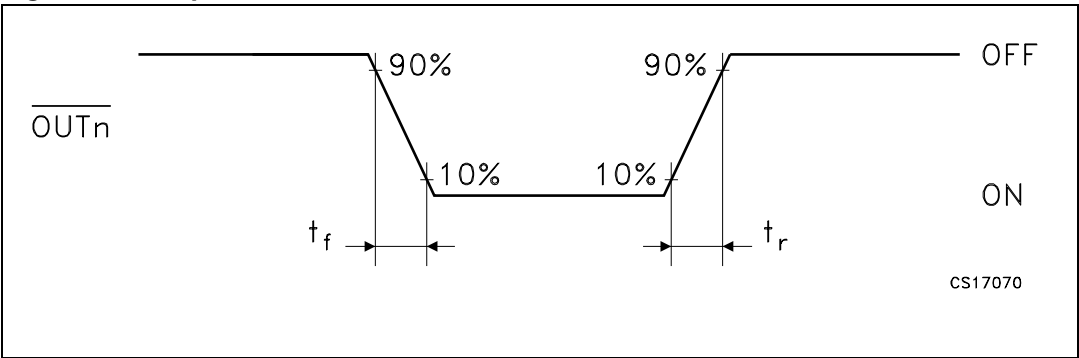


Figure 10. Outputs



6 Typical characteristics

Figure 11. Output current- R_{EXT} resistor

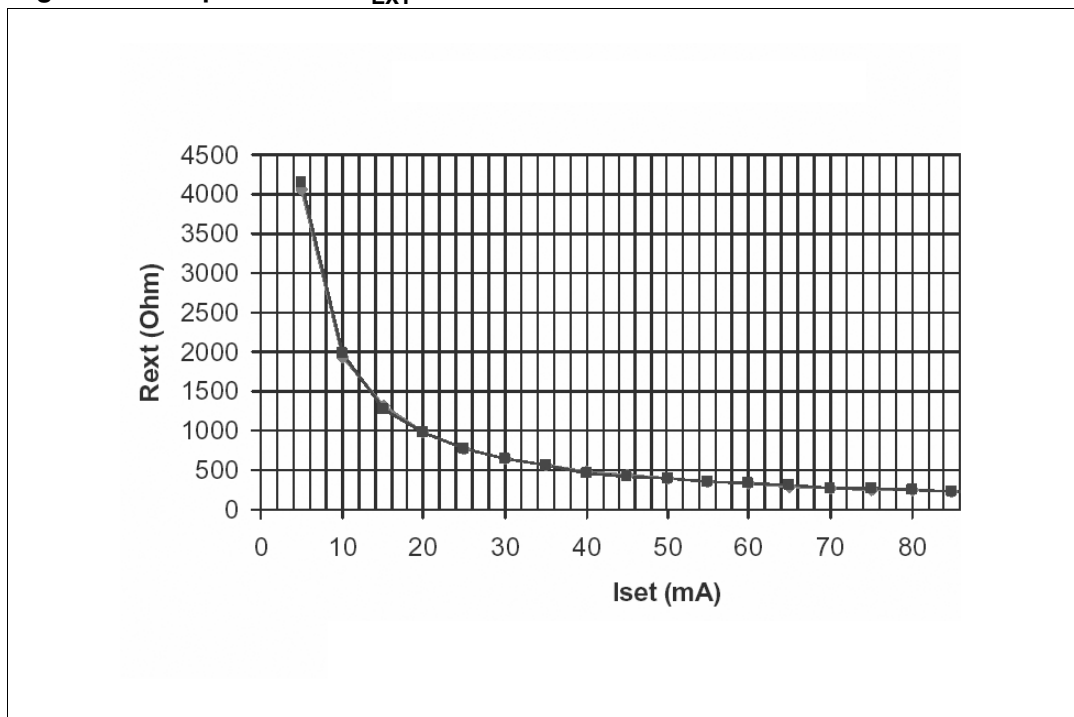


Table 10. Output current- R_{EXT} resistor

R_{ext} (Ohm)	Output current (mA)
976	20
780	25
652	30
560	35
488	40
433	45
389	50
354	55
325	60
300	65
278	70
259	75
241	80
229	85
215	90

Figure 12. Output current vs $\pm \Delta I_{OL}(\%)$

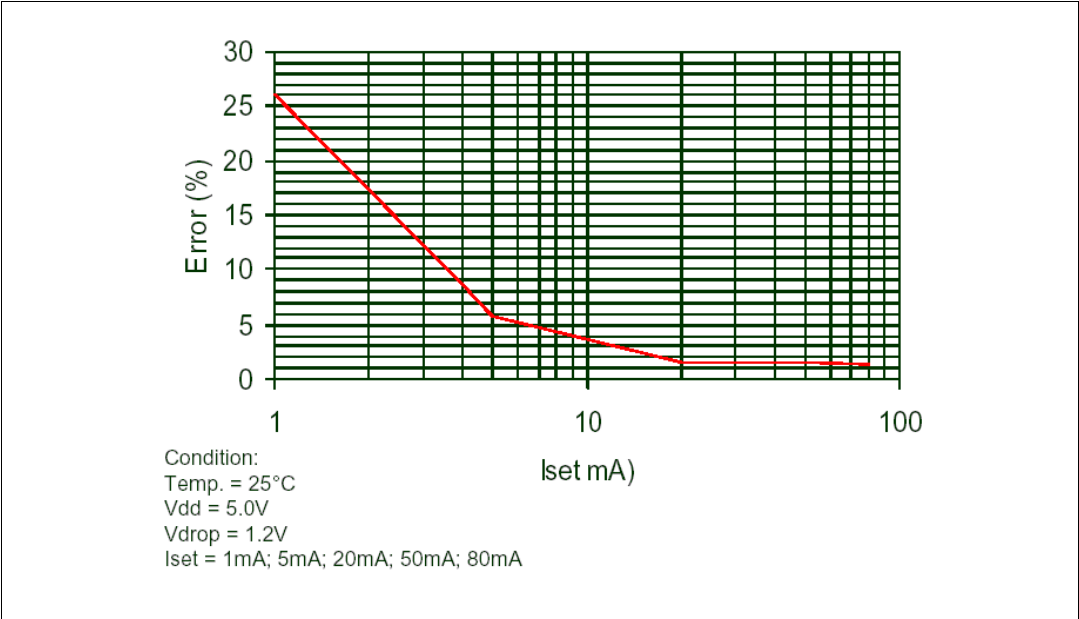


Figure 13. I_{SET} vs drop out voltage (V_{drop})

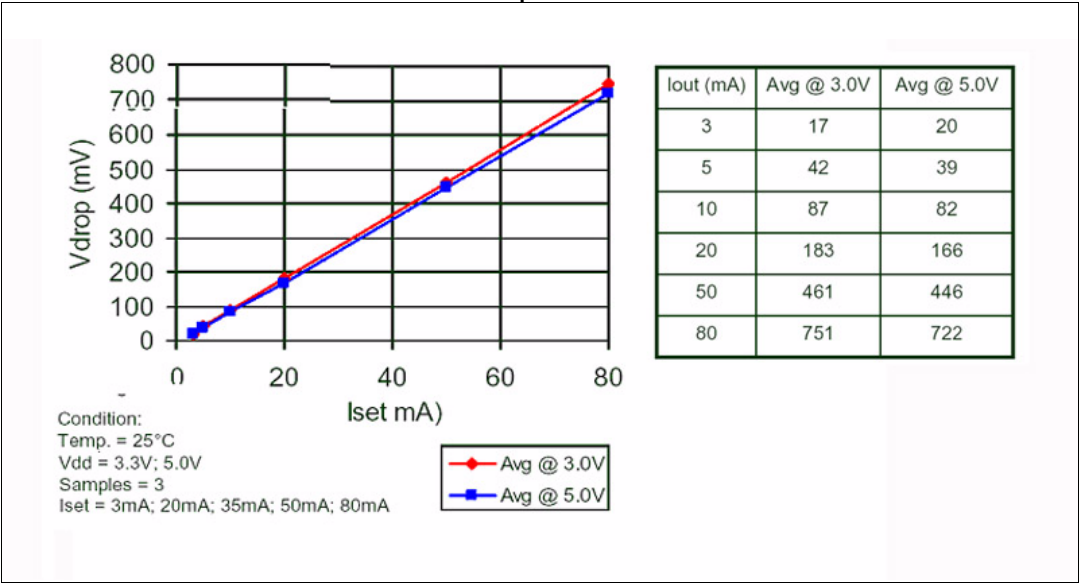


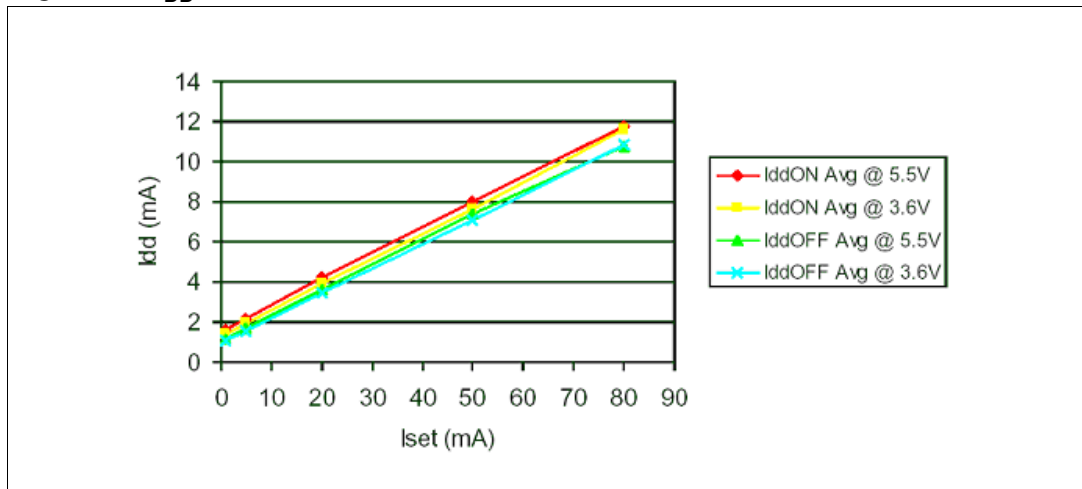
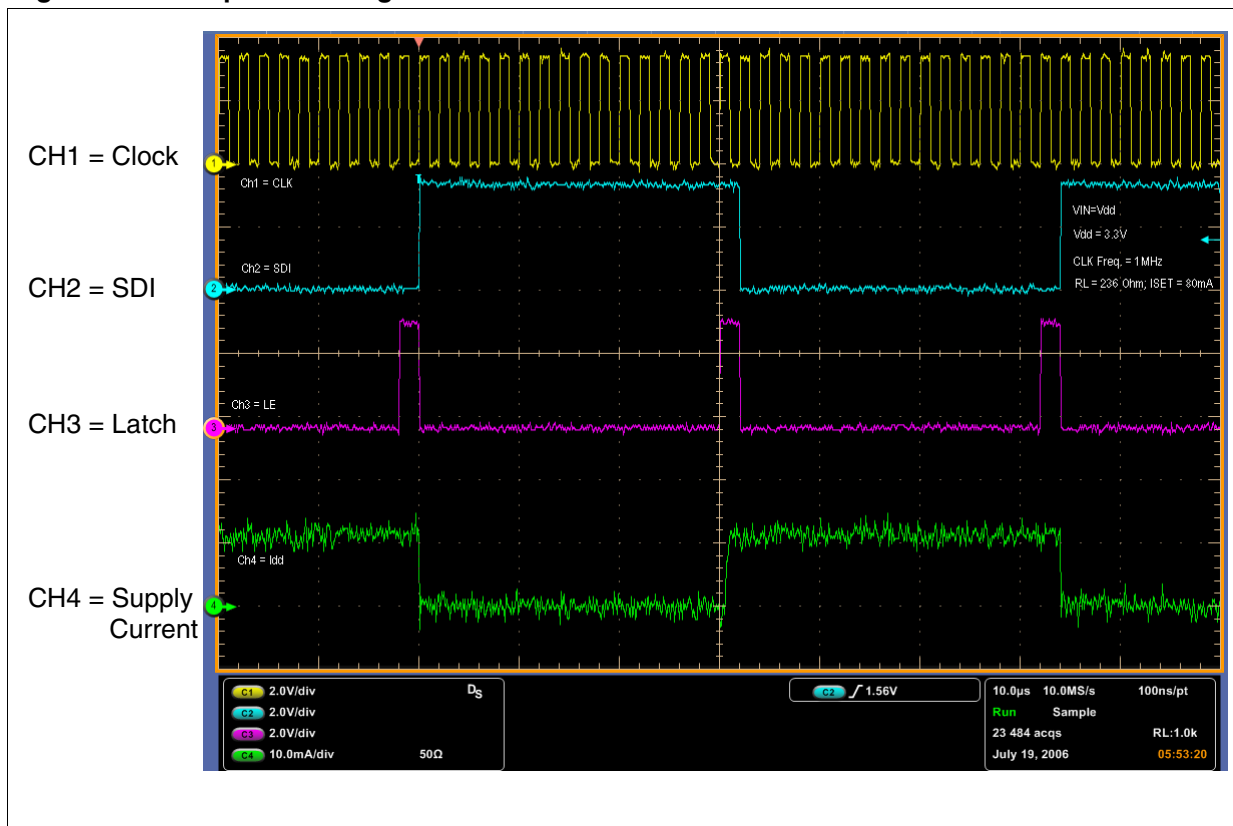
Figure 14. I_{DD} ON/OFF

Figure 15. Auto power saving



Note: Auto power-saving feature minimizes the quiescent current if no active data is detected on the latches and auto-power-up the device at fist active data latched.

7 Test circuit

Figure 16. DC characteristic

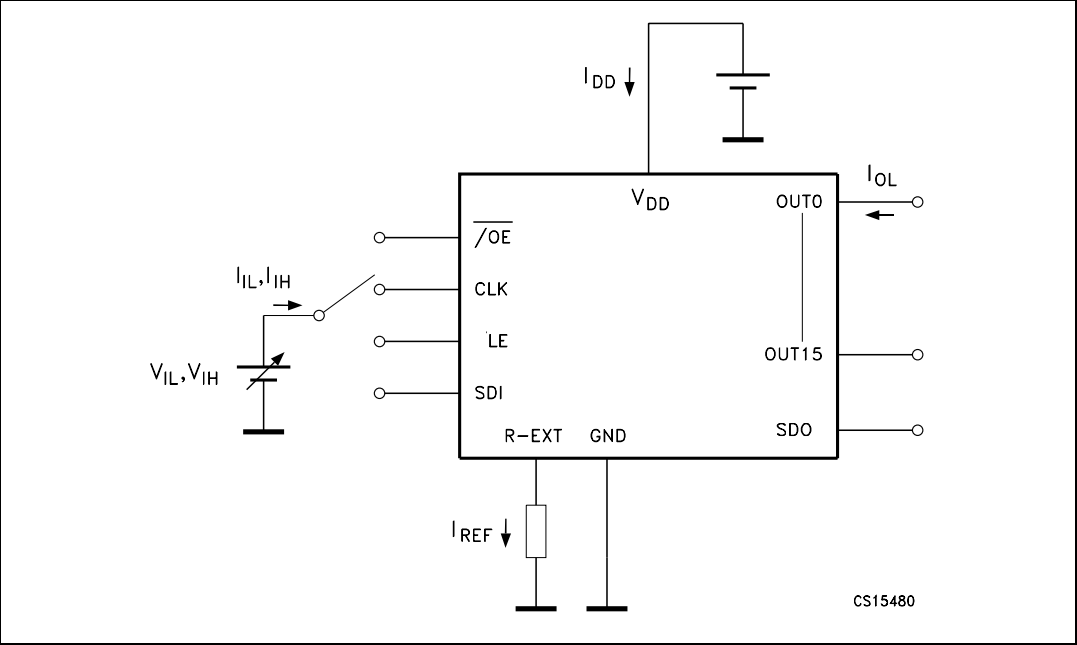


Figure 17. AC characteristic

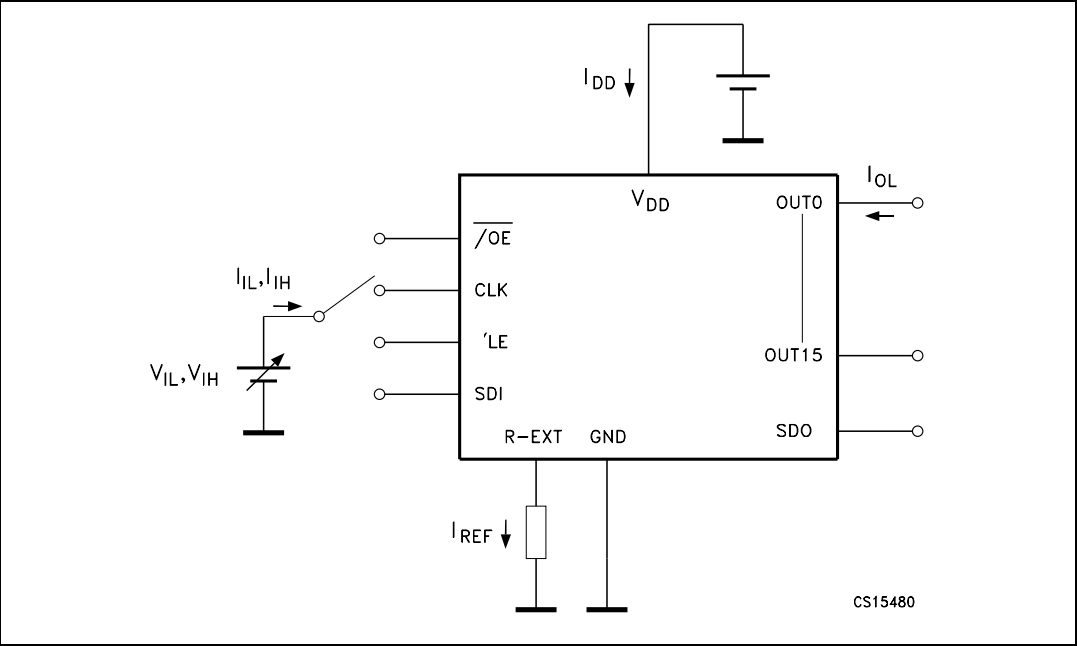
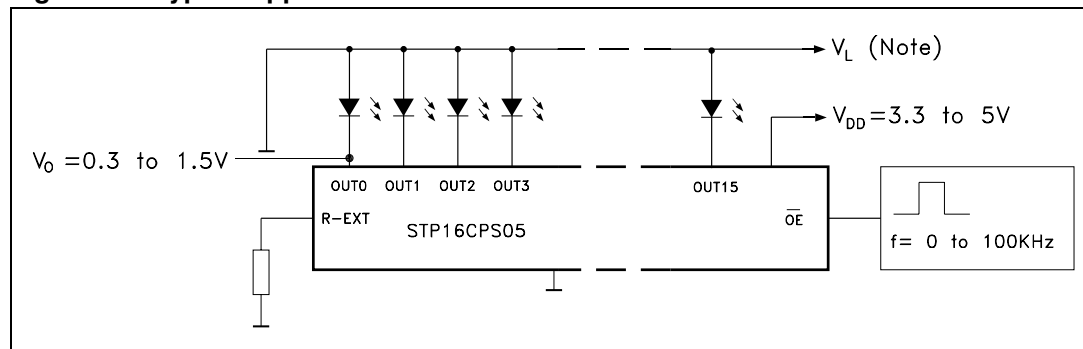


Figure 18. Typical application schematic



Note: V_L will be determined by the V_F of the LEDs

Test condition: Temp. = 25°C, V_{DD} = 3.0V, V_{IN} = V_{DD} , C_L = 10pF, Freq. = 1MHz, Ch1 = CLK, Ch2 = SDI, Ch3 = OUTn, Ch4 = V_{OUT}

Figure 19. Turn ON output current setup

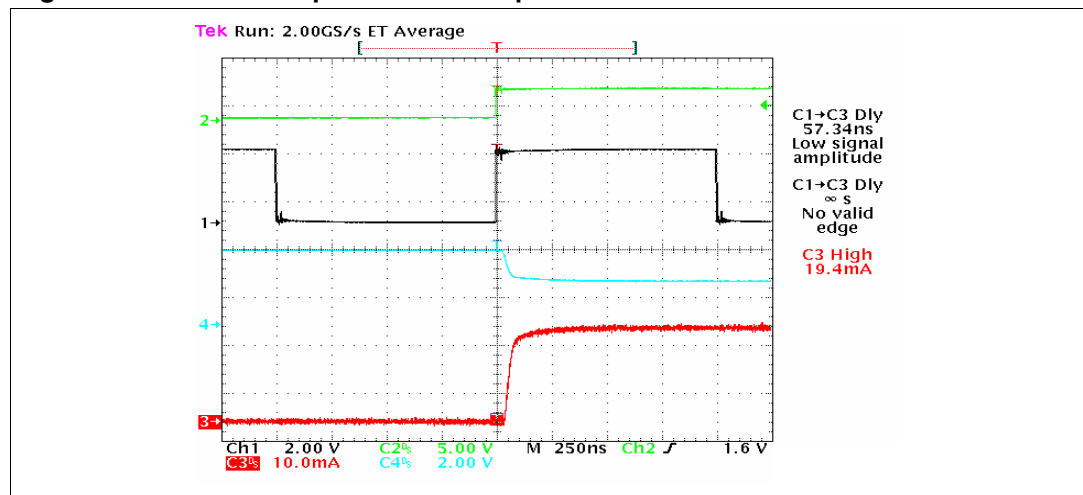
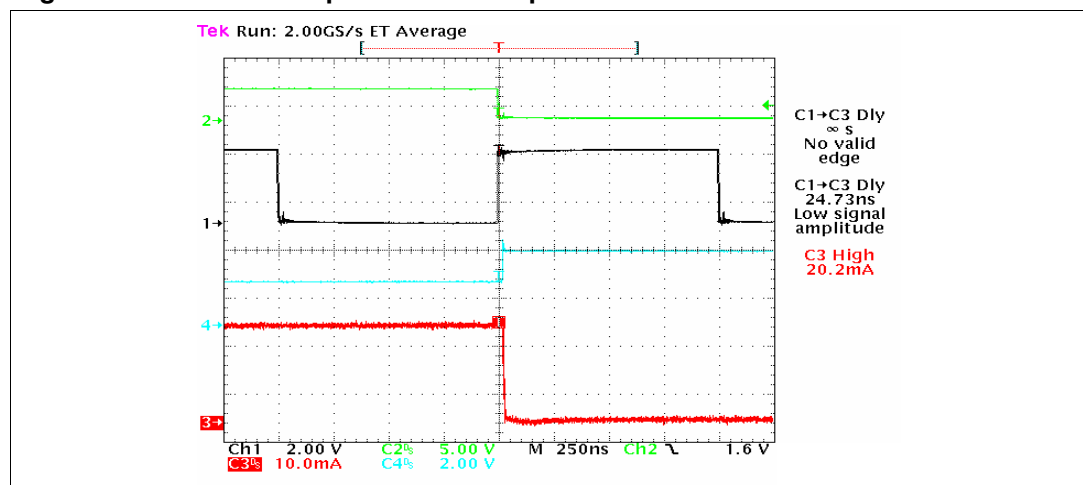


Figure 20. Turn OFF output current setup



8 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

Table 11. Plastic DIP-24 (0.25) mechanical data

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A			4.32			0.170
A1	0.38			0.015		
A2		3.3			0.130	
B	0.41	0.46	0.51	0.016	0.018	0.020
B1	1.40	1.52	1.65	0.055	0.060	0.065
c	0.20	0.25	0.30	0.008	0.010	0.012
D	31.62	31.75	31.88	1.245	1.250	1.255
E	7.62		8.26	0.300		0.325
E1	6.35	6.60	6.86	0.250	0.260	0.270
e		2.54			0.100	
E1		7.62			0.300	
L	3.18		3.43	0.125		0.135
M	0°		15°	0°		15°

Figure 21. Plastic DIP-24 (0.25) package dimensions

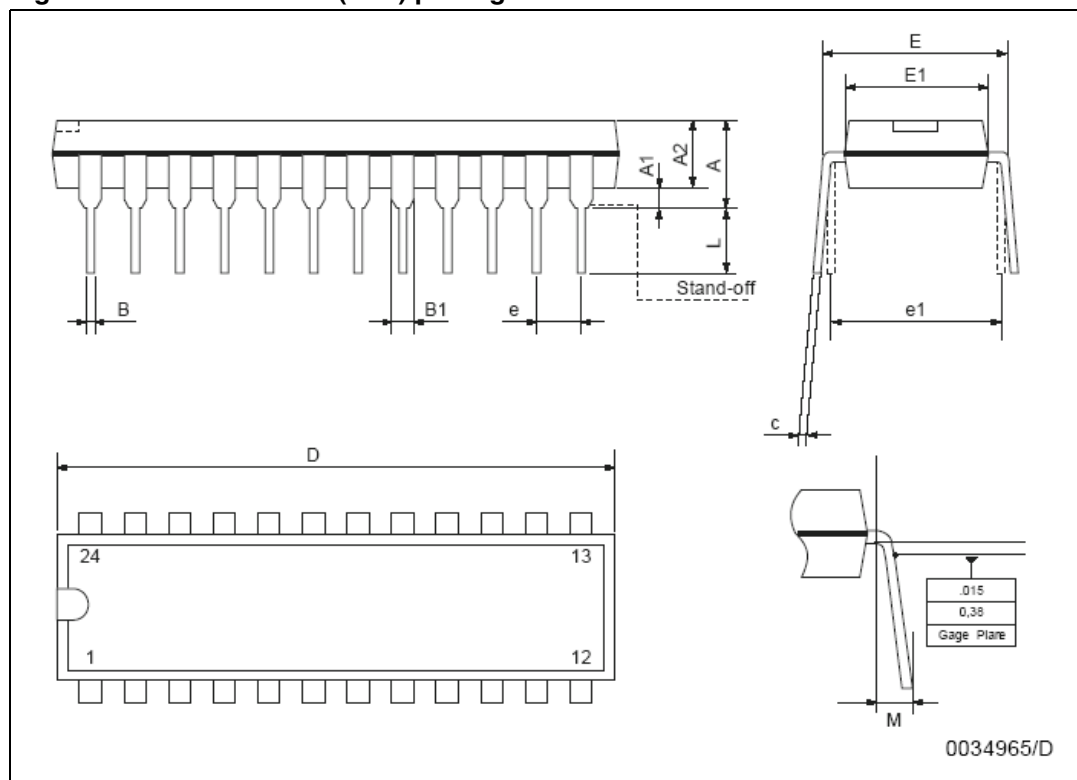


Table 12. TSSOP24 mechanical data

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A			1.1			0.043
A1	0.05		0.15	0.002		0.006
A2		0.9			0.035	
b	0.19		0.30	0.0075		0.0118
c	0.09		0.20	0.0035		0.0079
D	7.7		7.9	0.303		0.311
E	4.3		4.5	0.169		0.177
e		0.65 BSC			0.0256 BSC	
H	6.25		6.5	0.246		0.256
K	0°		8°	0°		8°
L	0.50		0.70	0.020		0.028

Figure 22. TSSOP24 Package dimensions

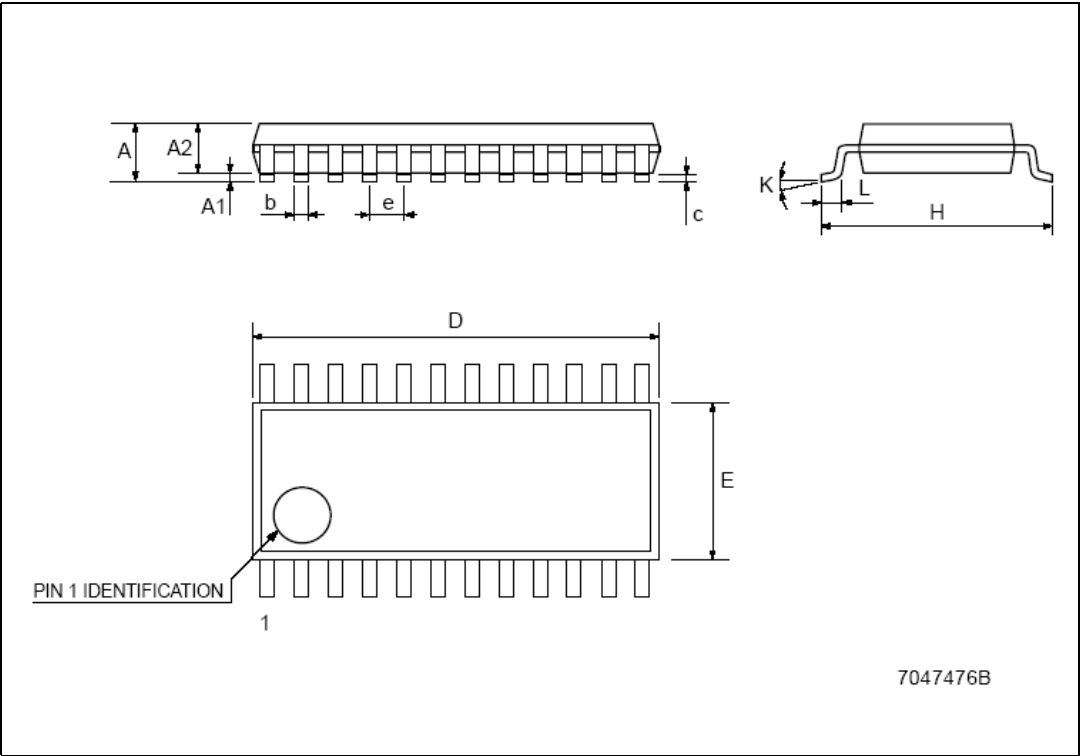


Table 13. Tape & Reel TSSOP24

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A			330			2.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	6.8		7	0.268		0.276
Bo	8.2		8.4	0.323		0.331
Ko	1.7		1.9	0.067		0.075
Po	3.9		4.1	0.153		0.161
P	11.9		12.1	0.468		0.476

Figure 23. Reel dimensions

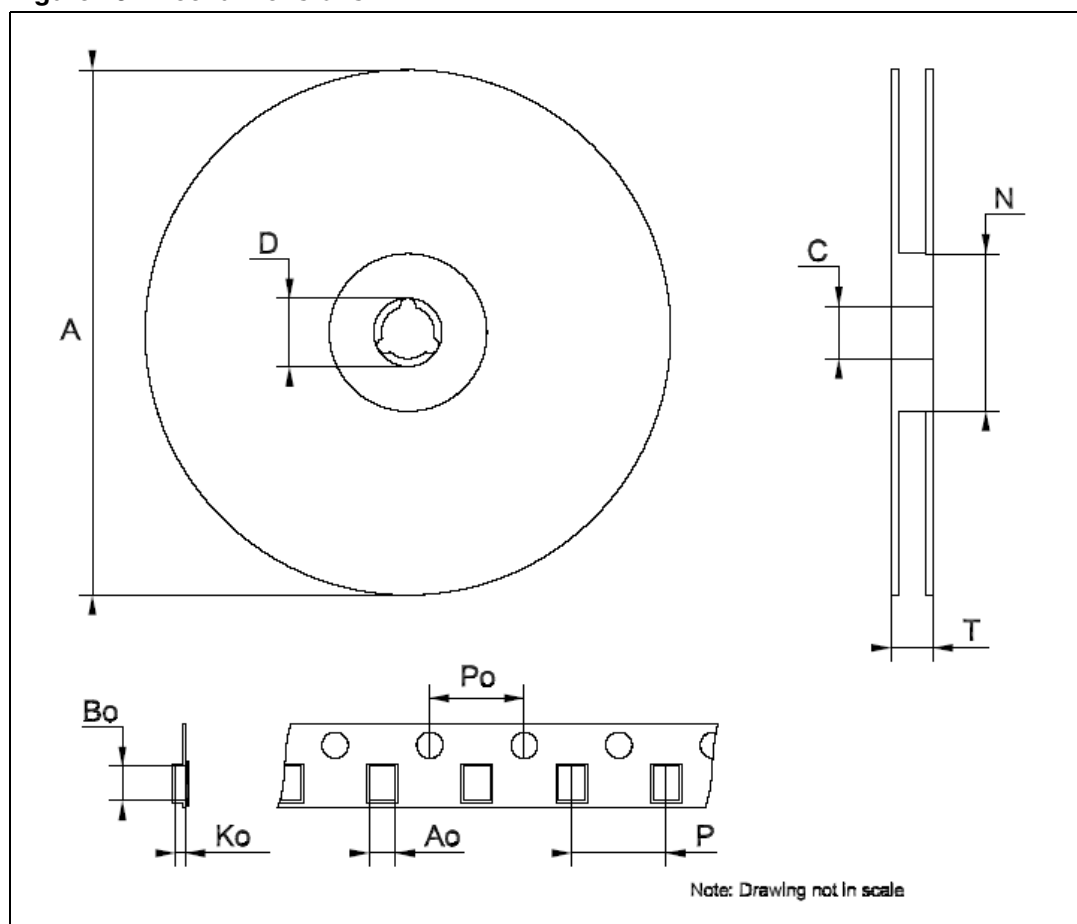


Table 14. SO-24 mechanical data

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A			2.65			0.104
a1	0.1		0.2	0.004		0.008
a2			2.45			0.096
b	0.35		0.49	0.014		0.019
b1	0.23		0.32	0.009		0.012
C		0.5			0.020	
c1	45°(typ.)					
D	15.20		15.60	0.598		0.614
E	10.00		10.65	0.393		0.419
e		1.27			0.050	
e3		13.97			0.550	
F	7.40		7.60	0.291		0.300
L	0.50		1.27	0.020		0.050
S	°(max.) 8					

Figure 24. SO-24 package dimensions

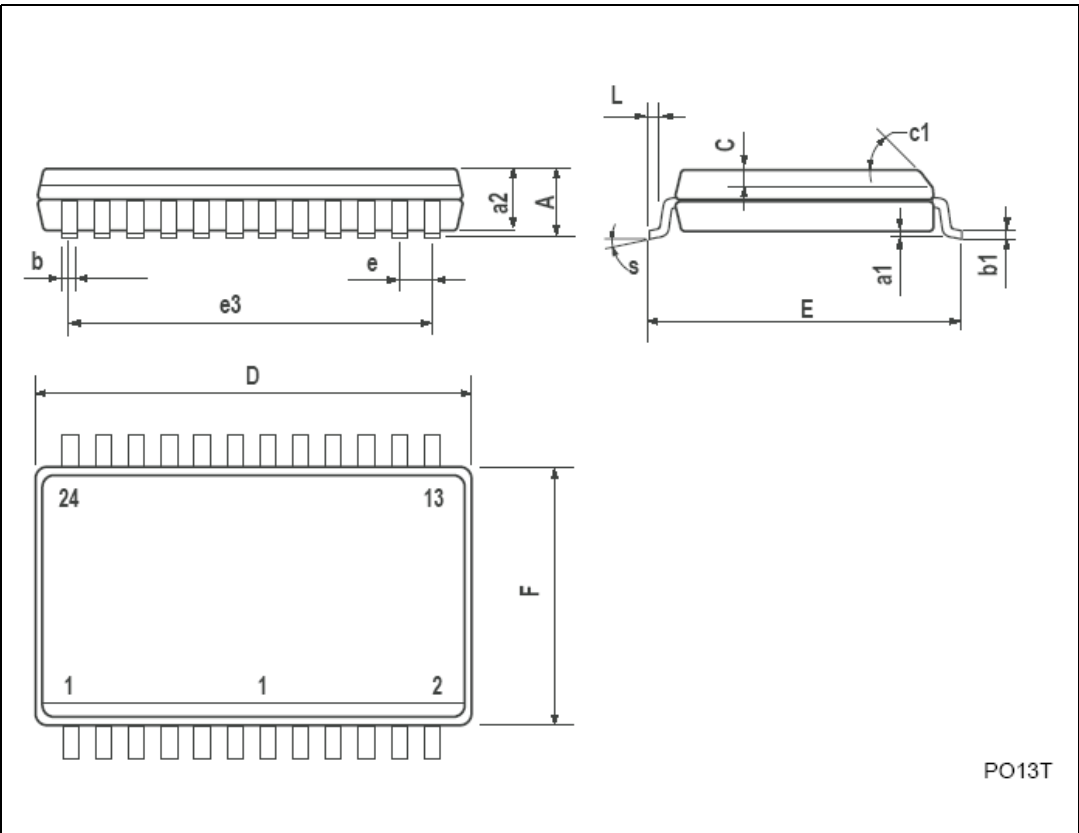


Table 15. Tape & Reel SO-24

Dim.	mm.			inch		
	Min.	Typ	Max.	Min.	Typ.	Max.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			30.4			1.197
Ao	10.8		11.0	0.425		0.433
Bo	15.7		15.9	0.618		0.626
Ko	2.9		3.1	0.114		0.122
Po	3.9		4.1	0.153		0.161
P	11.9		12.1	0.468		0.476

Figure 25. Reel dimensions

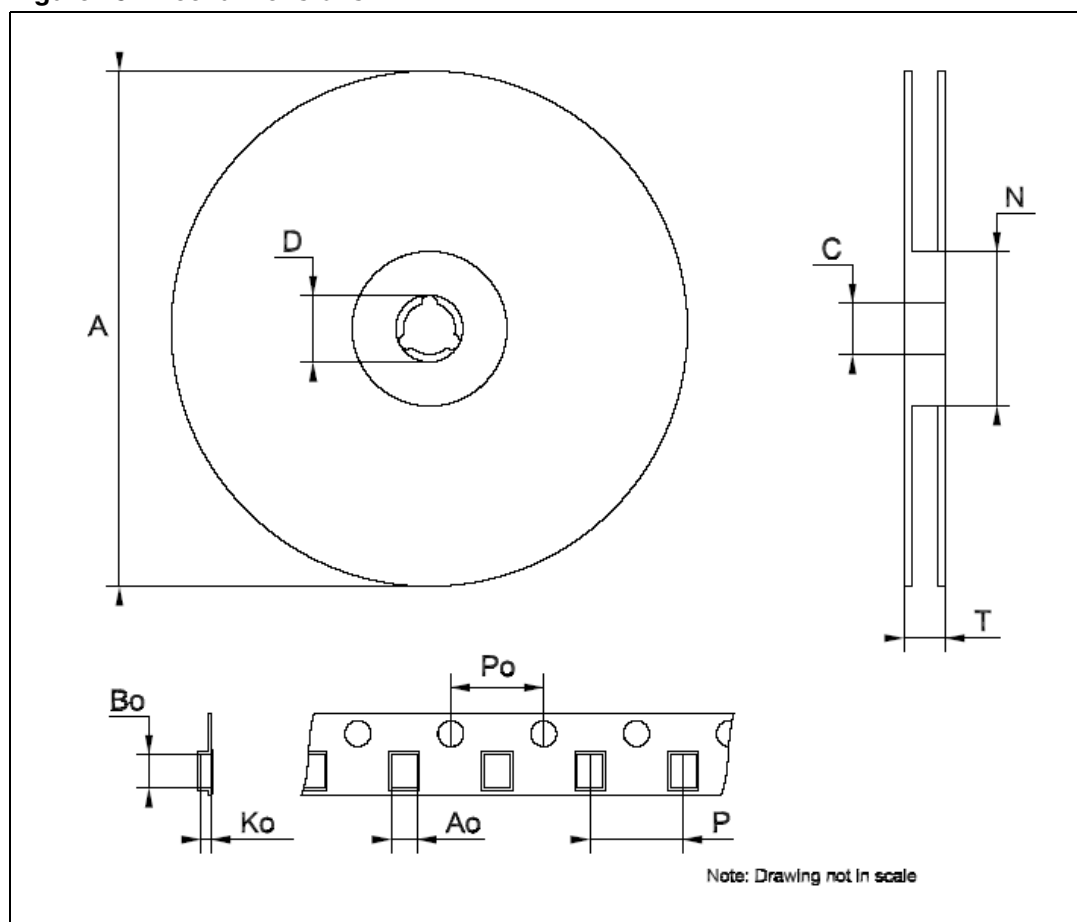
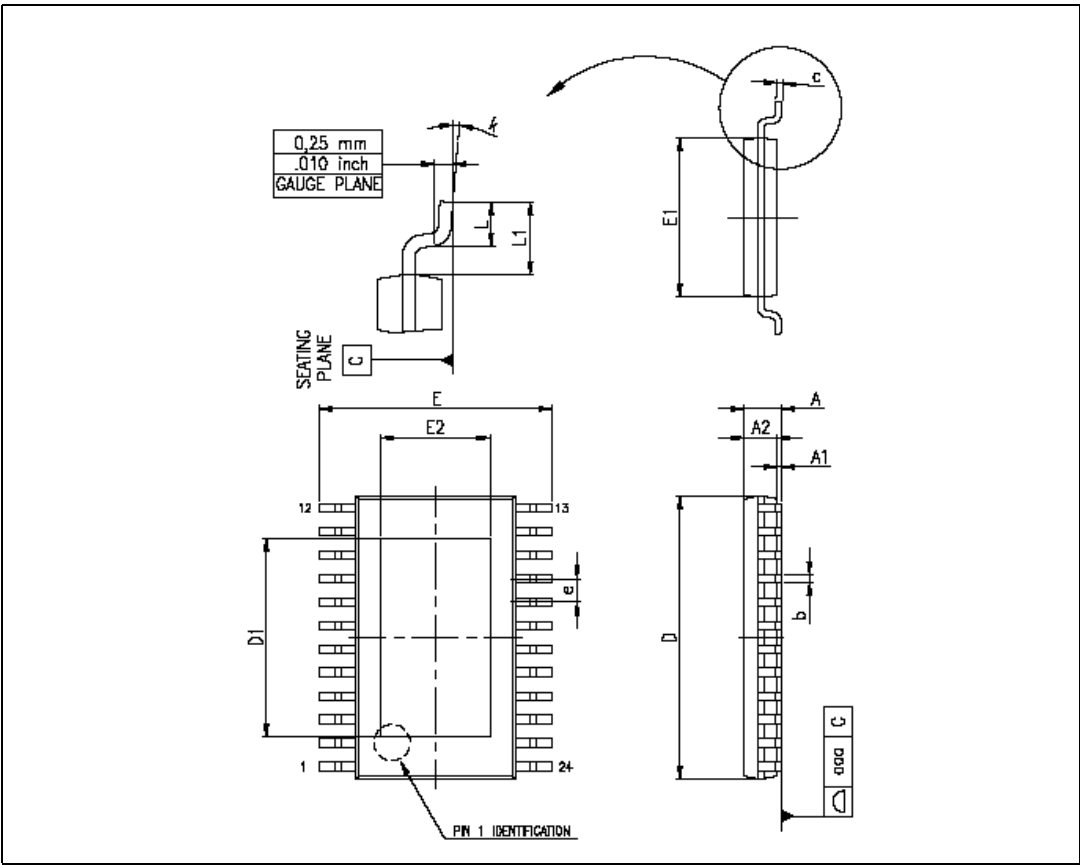


Table 16. TSSOP24 exposed-pad

Dim.	mm			inch		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.2			0.047
A1			0.15		0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	7.7	7.8	7.9	0.303	0.307	0.311
D1		2.7		0.106		
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.5	0.169	0.173	0.177
E2		1.5		0.059		
e		0.65			0.0256	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030

Figure 26. TSSOP24 Dimensions



9 Revision history

Table 17. Revision history

Date	Revision	Changes
28-Jul-2006	1	First release
22-Dec-2006	2	Final datasheet

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2006 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com